

PMP9126 Rev B Bill Of Materials

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C1, C2, C3, C4	4	2.2uF	CAP, CERM, 2.2uF, 100V, +/-10%, X7R, 1210	1210	GRM32ER72A225KA35L	MuRata
C5	1	0.033uF	CAP, CERM, 0.033uF, 250V, +/-10%, X7R, 1206	1206	GRM31CR72E333KW03L	MuRata
C7, C14, C20	3	0.1uF	CAP, CERM, 25V, +/-10%, X7R, 0402	0402	STD	STD
C8, C9, C10, C12, C13, C26, C27, C28, C29, C30, C31	11	47uF	CAP, CERM, 16V, +/-20%, X5R, 1210	1210	C1210C476M4	Kemet
C11, C16	2	22uF	CAP, CERM, 25V, +/-10%, X7R, 1210	1210	STD	STD
C15	1	47pF	CAP, CERM, 50V, +/-10%, X7R, 0402	0402	STD	STD
C17	1	0.047uF	CAP, CERM, 25V, +/-10%, X7R, 0402	0402	STD	STD
C18	1	1000pF	CAP, CERM, 1000pF, 3kV, 1808	1808	STD	STD
C19	1	1000pF	CAP, CERM, 25V, +/-10%, X7R, 0402	0402	STD	STD
C21, C22	2	1uF	CAP, CERM, 16V, +/-10%, X5R, 0402	0402	STD	STD
C23	1	100pF	CAP, CERM, 50V, +/-10%, X7R, 0402	0402	STD	STD
C24	1	4700pF	CAP, CERM, 50V, +/-10%, X7R, 0402	0402	STD	STD
C25	1	10uF	CAP, CERM, 16V, +/-10%, X5R, 1206	1206	STD	STD
C100	1	0.047uF	CAP, CERM, 50V, +/-10%, X7R, 0603	0603	STD	STD
D1	1	100V	Diode, Switching, 100V, 0.2A, SOD-123	SOD-123	MMSD4148T1G	ON Semiconductor
D2	1	5.1V	Diode, Zener, 5.1V, 500mW, SOD-123	SOD-123	MMSZ4689-V	Vishay-Semiconductor
D3, D4, D5, D6, D7	5	1.4V	Diode, Ultrafast, 100V, 0.25A, SOD-323	SOD-323	BAS316, 115	NXP Semiconductor
D100	1	0.88V	DIODE ULTRA FAST 100V 2A SMA	SMA	MURA110	ON Semi
L1	1	3.3uH	Inductor, Shielded, Composite, 3.3uH, 25A, 0.0037 ohm, SMD	Inductor, 11.3x10x10mm	XAL1010-332MEB	Coilcraft
L2	1	1mH	Inductor, Shielded Drum Core, Ferrite, 1mH, 0.11A, 16.3 ohm, SMD	LPS4414	LPS4414-105MLB	Coilcraft
Q1	1	0.7V	Transistor, NPN, 65V, 0.1A, SOT-23	SOT-23	BC846BLT1G	ON Semiconductor
Q2	1	30V	MOSFET, N-CH, 30V, 100A, SON 5x6mm	SON 5x6mm	CSD17501Q5A	Texas Instruments
Q3	1	-30V	MOSFET P-CH 150V 2.2A 8-SOIC	SOIC-8	IRF6216TRPBF	International Rectifier
Q4	1	40V	MOSFET, N-CH, 40V, 100A, SON 5x6mm	SON 5x6mm	CSD18502Q5B	Texas Instruments
Q5	1	150V	MOSFET, N-CH, 150V, 35A, PQFN08A	PQFN08A	FDMS86200	Fairchild Semiconductor
Q6	1	0.25V	Transistor, PNP, 40V, 0.2A, SOT-23	SOT-23	MMBT3906	Fairchild Semiconductor
R1	1	511	RES, 1%, 0.125W, 0805	0805	STD	STD
R3	1	10	RES, 1%, 0.1W, 0603	0603	STD	STD
R4, R22, R24	3	10k	RES, 1%, 0.063W, 0402	0402	STD	STD
R5, R15, R17	3	0	RES, 1%, 0.063W, 0402	0402	STD	STD
R6, R18, R20, R21, R23	5	1k	RES, 1%, 0.063W, 0402	0402	STD	STD
R7	1	191k	RES, 1%, 0.063W, 0402	0402	STD	STD
R8	1	80.6k	RES, 1%, 0.063W, 0402	0402	STD	STD
R9	1	20k	RES, 1%, 0.063W, 0402	0402	STD	STD
R10, R16	2	100k	RES, 1%, 0.063W, 0402	0402	STD	STD
R11	1	0.068	RES, 1%, 1W, 2010	2010	STD	STD
R12, R13	2	3.01k	RES, 1%, 0.063W, 0402	0402	STD	STD
R14	1	90.9k	RES, 1%, 0.063W, 0402	0402	STD	STD
R19	1	750	RES, 1%, 0.1W, 0603	0603	STD	STD
R25	1	3.16k	RES, 1%, 0.063W, 0402	0402	STD	STD
R100	1	1.82k	RES, 1%, 1W, 2512	2512	STD	STD
T1	1	153uH	Transformer, High Frequency Flat Coil Planar, SMT	920x910x850mil	PH0806.005NL	Pulse Engineering
TP1, TP2	2		PCB Pin, solderless Pressfit, Tin over Nickel	PCB Pin	8600-0-05-80-00-00-03-0	Mill-Max
TP3, TP4	2		PCB Pin, solderless Pressfit, Tin over Nickel	PCB Pin	8952-0-05-80-00-00-03-0	Mill-Max
U1	1		Single-Channel High-Speed Low-Side Gate Driver (with 4-A Peak Source and 8-A Peak Sink), DBV0006A	DBV0006A	UCC27511DBV	Texas Instruments
U2	1		Advanced Active Clamp PWM Controller with Current Control, -40 to +125 degC, 20-pin QFN (RGP), Green (RoHS & no Sb/Br)	RGP0020D	UCC2897ARGPR	Texas Instruments
U3	1		OPTOCOUPLER PHOTOTRANS 125% 4LSOP	8x2x4mm	VOL618A-2T	Vishay-Semiconductor
U4	1		LOW-VOLTAGE ADJUSTABLE PRECISION SHUNT REGULATOR, DBZ0003A	DBZ0003A	TLV431AIDBZ	Texas Instruments

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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